

IN THE SPECIFICATION

Please amend the paragraph of the specification from page 3, line 17 to page 4, line 2 as follows:

--However, the above-mentioned heat transfer structure of a light emitting device has the following problems. The adhesive filler made mainly of silicone resin and having high thermal conductivity is used to conduct the heat generated in the LED chip, but it has a smaller thermal conductivity than a material such as a metal or a ceramic. Further, at least a step for filling the filler into the holes for forming heat transfer paths is needed in a packaging process thereof, besides a step for mounting the LED packages 90 to the lands 93. Further, the filling step is troublesome.--

Please amend the paragraph of the specification from page 8, line 1 to line 9 as follows:

--In another aspect of the invention, the light-emitting device further comprises a second plate for heat transfer bonded thermally to a second plane of the submount different from the first plane thereof besides the first plate for heat transfer. Thus the heat generated in the light-emitting diode chip can be transferred in two ways through ~~though~~ the first and second plates. The heat transfer means heat conduction through the solid materials between the submount and the first or second plate for heat transfer.--